

2017 Spring

“Calculation and Applications Phase Equilibria”
Principles *of* Solidification

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Contents for previous class

Solidification: Liquid \rightarrow Solid

< Nucleation in Pure Metals >

* Homogeneous Nucleation

$$r^* = \frac{2\gamma_{SL}}{\Delta G_V}$$

$$\Delta G^* = \frac{16\pi\gamma_{SL}^3}{3(\Delta G_V)^2} = \left(\frac{16\pi\gamma_{SL}^3 T_m^2}{3L_V^2} \right) \frac{1}{(\Delta T)^2}$$

r^* & ΔG^* \downarrow as $\Delta T \uparrow$

$$N_{hom} \approx f_0 C_o \exp\left\{-\frac{A}{(\Delta T)^2}\right\}$$

changes by orders of magnitude from zero to very high values over a very narrow temp. range

* Heterogeneous Nucleation

$$\Delta G_{het}^* = S(\theta)\Delta G_{hom}^*$$

$$\frac{V_A}{V_A + V_B} = \frac{2 - 3\cos\theta + \cos^3\theta}{4} = S(\theta)$$

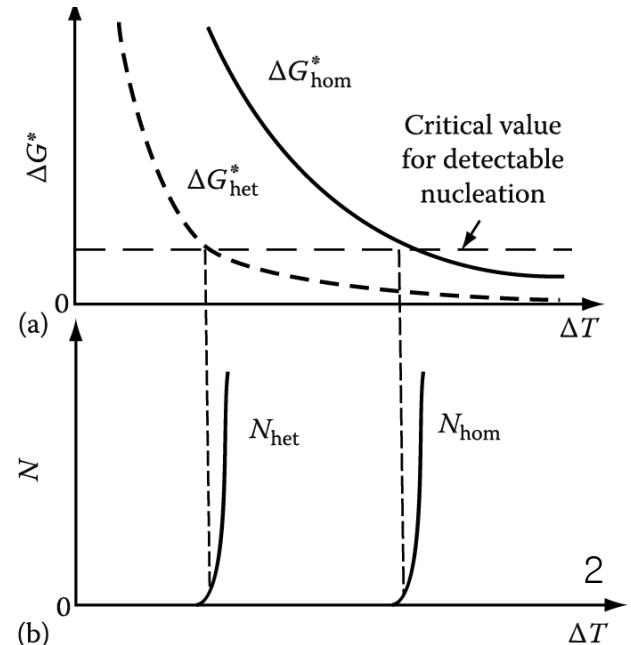
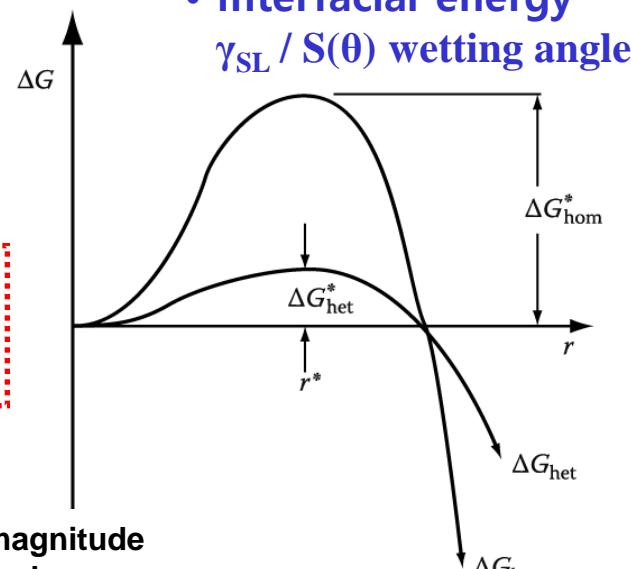
* Nucleation of melting

$$\gamma_{SL} + \gamma_{LV} < \gamma_{SV}$$

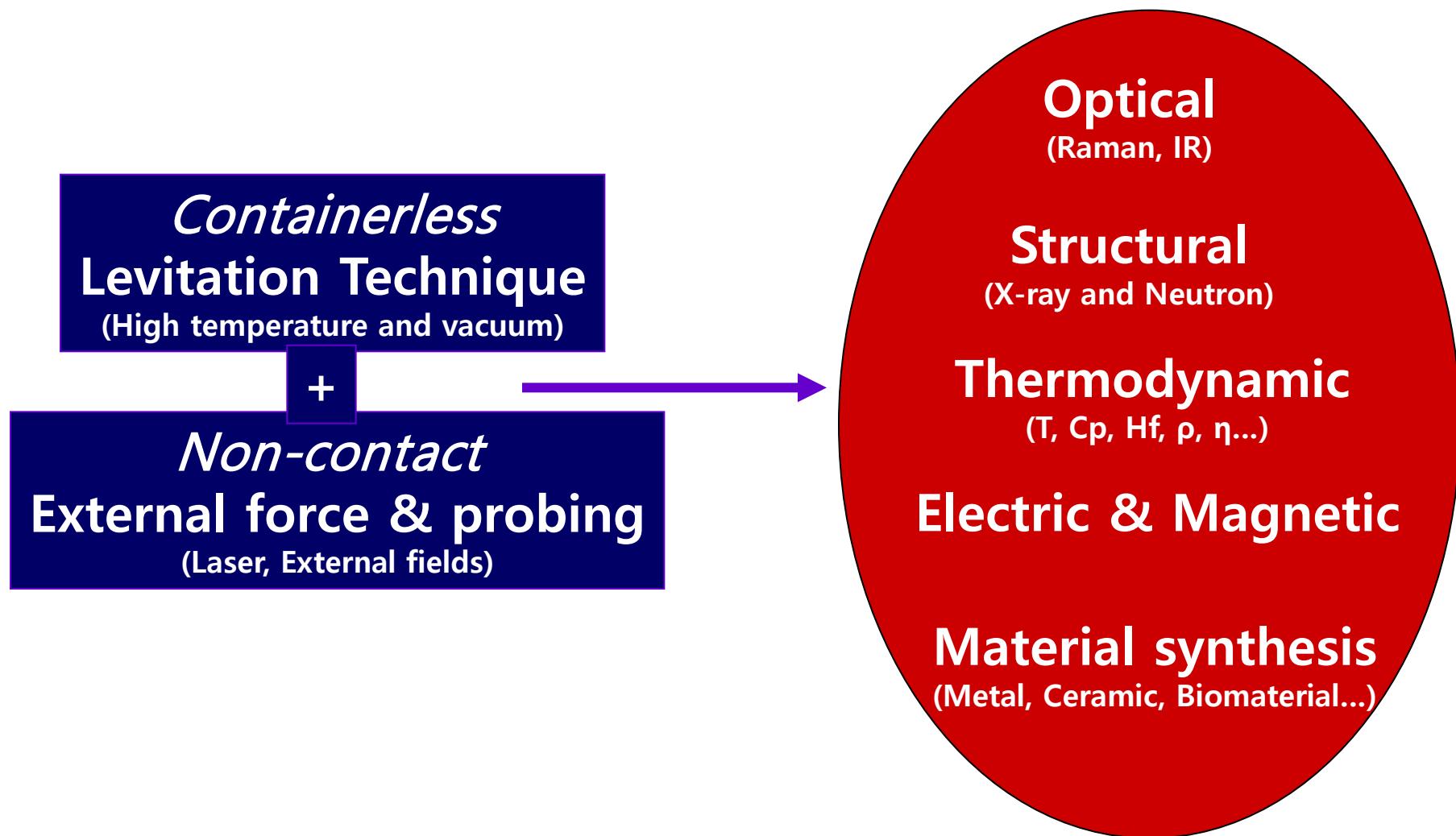
(commonly)

- Undercooling ΔT

- Interfacial energy $\gamma_{SL} / S(\theta)$ wetting angle



Containerless and Contactless Measurement System

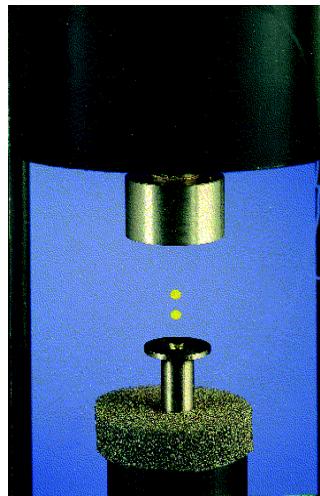
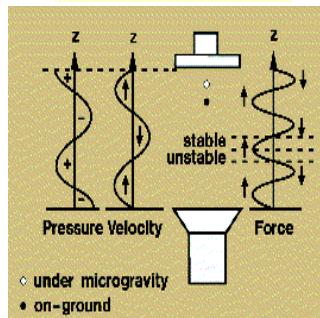


High Temperature Levitation

Ultra-high temperature $> 3000 \text{ }^{\circ}\text{C}$

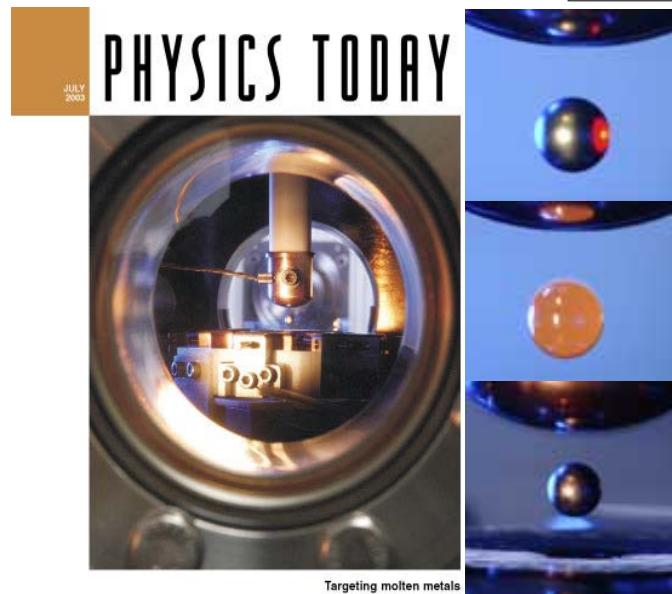
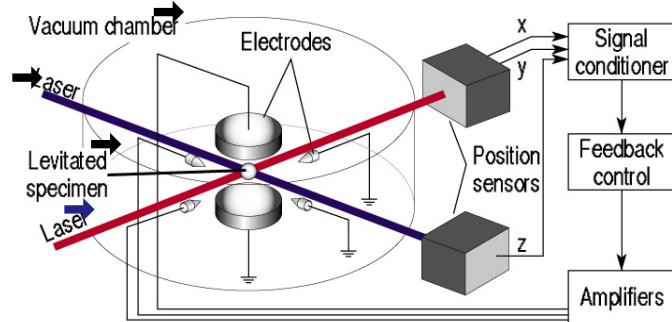
* Magnetic/diamagnetic/superconducting levitation → Only magnetic sample, below T_c

Acoustic



Requirement of acoustic media, Unstable at high T

Electrostatic



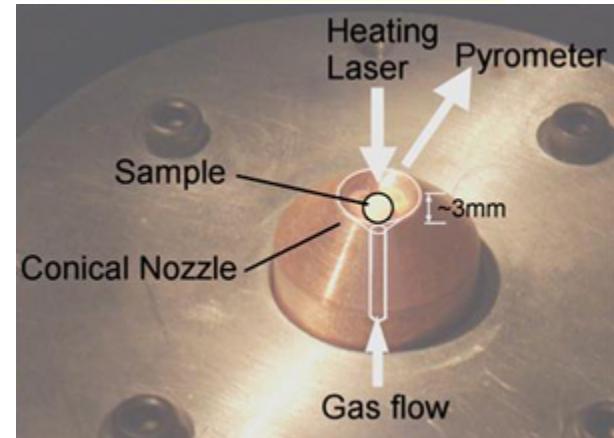
Physics Today, v56, p22, July 2003

All types of samples,
Suitable for sample heating

Electromagnetic



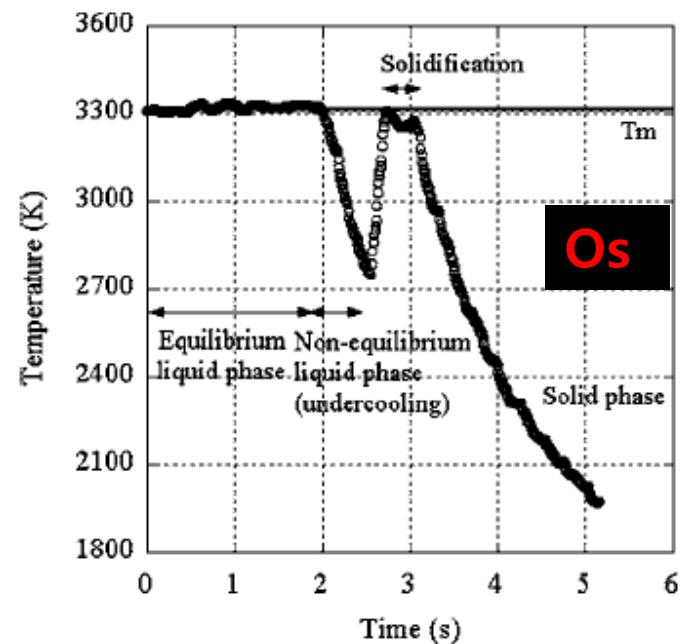
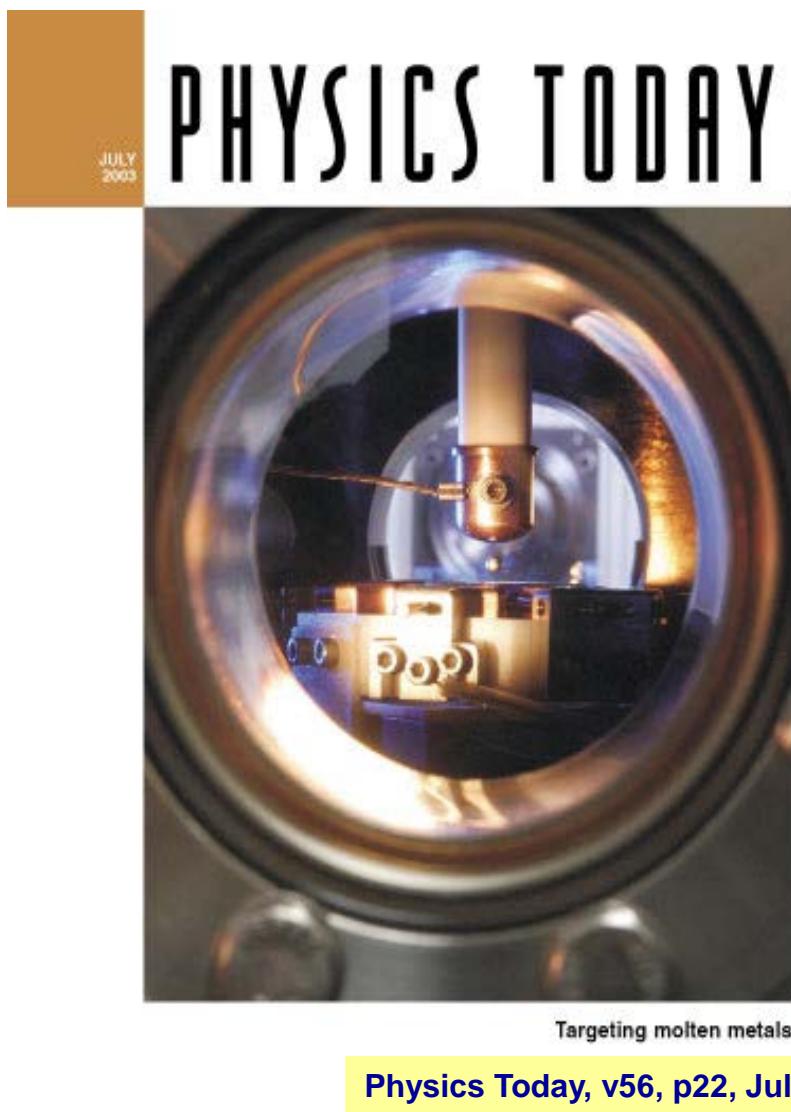
Only metallic & large mass sample
Aerodynamic



http://ec.europa.eu/research/industrial_technologies/articles/article_2288_en.html

Difficult to control rotation of sample,
Gas-sample reaction

Electrostatic Levitation (NASA, MSFC (Huntsville))



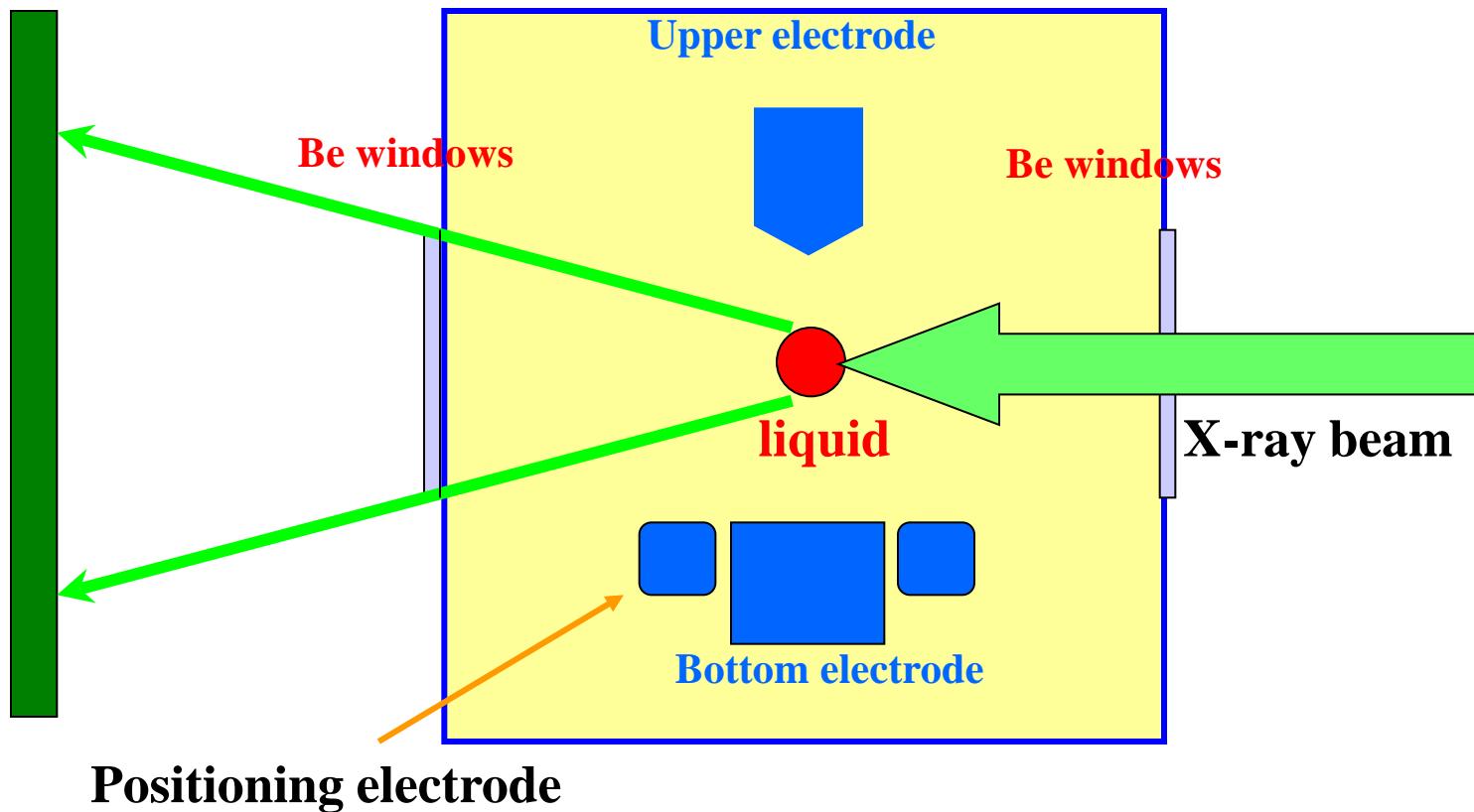
P.-F. Paradisa, et.al., JOURNAL OF APPLIED PHYSICS 100, 103523 2006

- Specific heat,
- Emissivity,
- Density,
- Viscosity,
- Surface tension...

Beam-ESL; High-energy synchrotron x-ray scattering experiment

Image plate detector

Vacuum Chamber



Sample size : 30-100 mg,
Temperature : 300-2200 K,

X-ray Energy : 125 keV,
Vacuum : 10^{-7} torr

Wavelength : 0.0988 \AA
Exposure time : 1 sec.

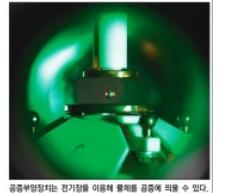
인공우주장치로 '건담 합금'도 가능할까

"직 전차를 한 방에 켜놓는 강력한 한탄을 만든다. 노드이나 휴대전화의 배터리 사용시간을 수십 배 늘린다." 자세에 차운적으로 존재하는 불길로는 이런 소리를 개발하기 어렵다. 지금보다 몇 배나 단단한 초금속, 전기저항성을 30배나 높인 물질이 있어야 하기 때문이다. 과학자들이 대신 찾은 곳은 우주 공간이다. 정확히 말하면 진짜 우주를 본존 '인공 우주'다.

진공을 만드는 것은 어렵지 않다. 풍靡 공기 흡수 냉각 있다. 그걸 어떻게 쓰려고 알아온다. 이 걸리는 시간과 품질은 위험을 내는 경기장을 헛되로 간다. 물론 전기 저항성이 상대적으로 강지 않은 물질을 10m의 시장면으로 우주인처럼 공중에 떠 놓았을 때 4000개가 지 가능할 수도 있다. 어려운 연구에는 우주로 끌어온 물체를 재생리하여 떠 있지도 않고 상당한 곳으로 뿐 아니라 날아온 고고했다. "마음에 에 실은 깨닫고 한 달 동안 미리하게 경기장을 예상된다"고 설명했다.

로봇을 신제품을 연구하고 있는 한국항공우주연구원은

이상석 책임연구원은 "중국은 재생리학 연구들에게 가 세계 8번의 건공-무중력 공간 구현 우주와 환경·우주사 각종 소형 가능 안개지는 금속-저강장 높린 배터리 등 '만화영화 같은 신소재 개발 기대'



공중부양장치는 진기장을 이용해 흡수를 공중에 쓰울 있다.

자는 이라는 물질이 결정 행위로 굳어 있기 때문인데 비해 물질은 결정을 이루지 않아 잘 깨지지 않는다. 이 기술은 현재 전자기 장치만. 미포일의 무부 고안한 테니스 리켓 등 다양한 형태를 만들 때 활용되고 있다. 일

본우주항공연구개발기구(NASA) 연구원은 2000여 미초 한 실험장치를 이용해 전기장장을 300~500㎚ 베터리 용 신물질을 개발했다.

시 국립 우주항공원은 우주에서도 진짜 우주를 할 수는 없다. 그레

는 유기체 달라야 한다. 다른 물질이 달아 있으니 달려의 실험장치와 오자고 생기다. 녹는점이 실기 3033℃에 달하는 스트루어 같은 물질은 달아를 용기조조 있다. 연구

구단이 개발한 공중부양장치는 이런 개개인 규칙을 극복해 '원의

실험'을 가능하게 한다. 주로 우주연구기관이 이 장치를 사용할 것으로 전망된다.

● 우주환경 구현... 우주환경 구현... 우주환경 구현...

1979년 소개된 만화영화 '기동전사 건담'의 우주환경 모션은 당시 '70-78-2'의 이름을 달면서 한 제작할 수 있는 특수효과 '후니타임'으로 만든다. 흥미로운 자료 사진



1979년 소개된 만화영화 '기동전사 건담'의 우주환경 모션은 당시 '70-78-2'의 이름을 달면서 한 제작할 수 있는 특수효과 '후니타임'으로 만든다. 흥미로운 자료 사진



우주환경 구현... 공중부양장치 개발
한국표준과학연구원

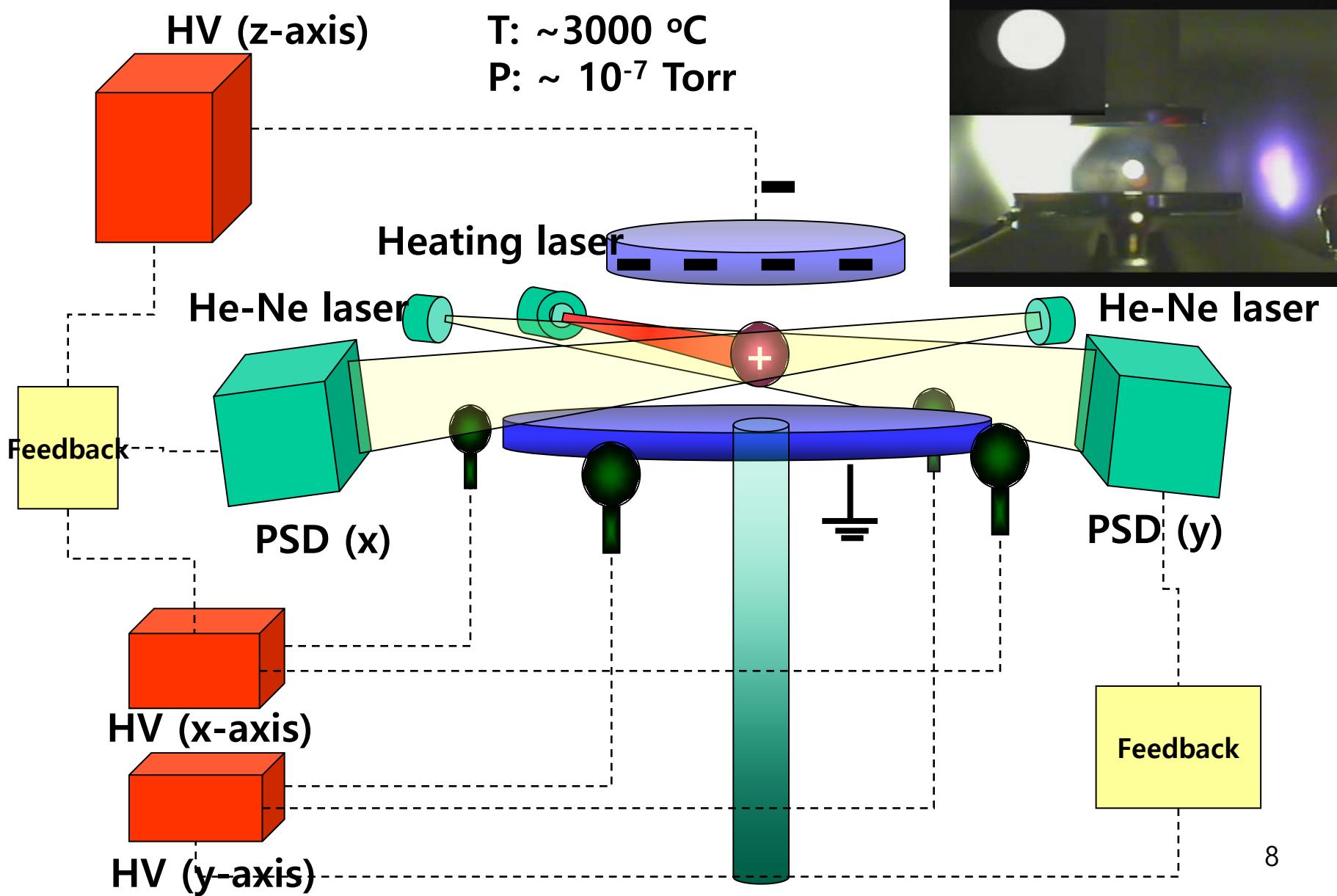


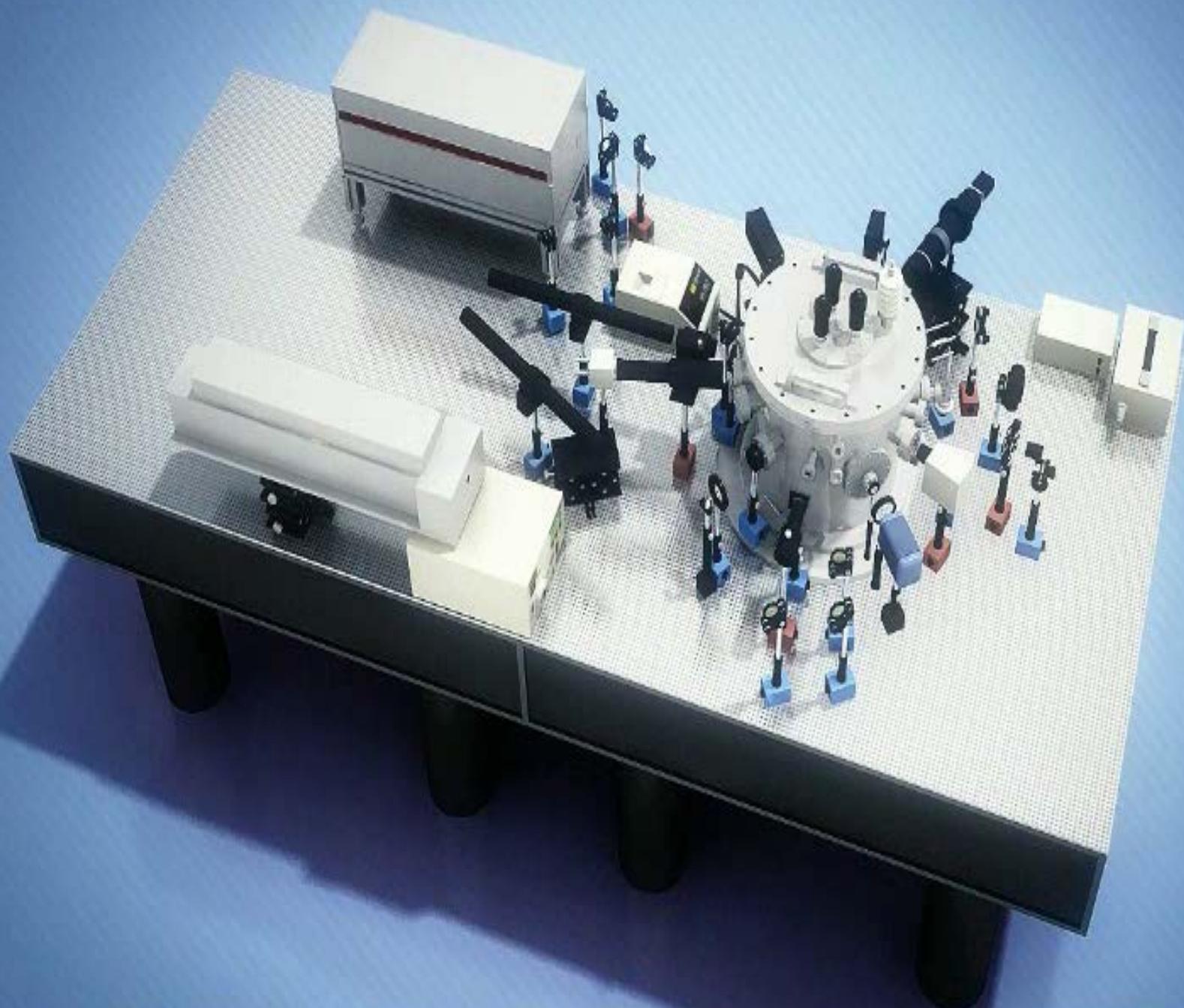
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0.3℃



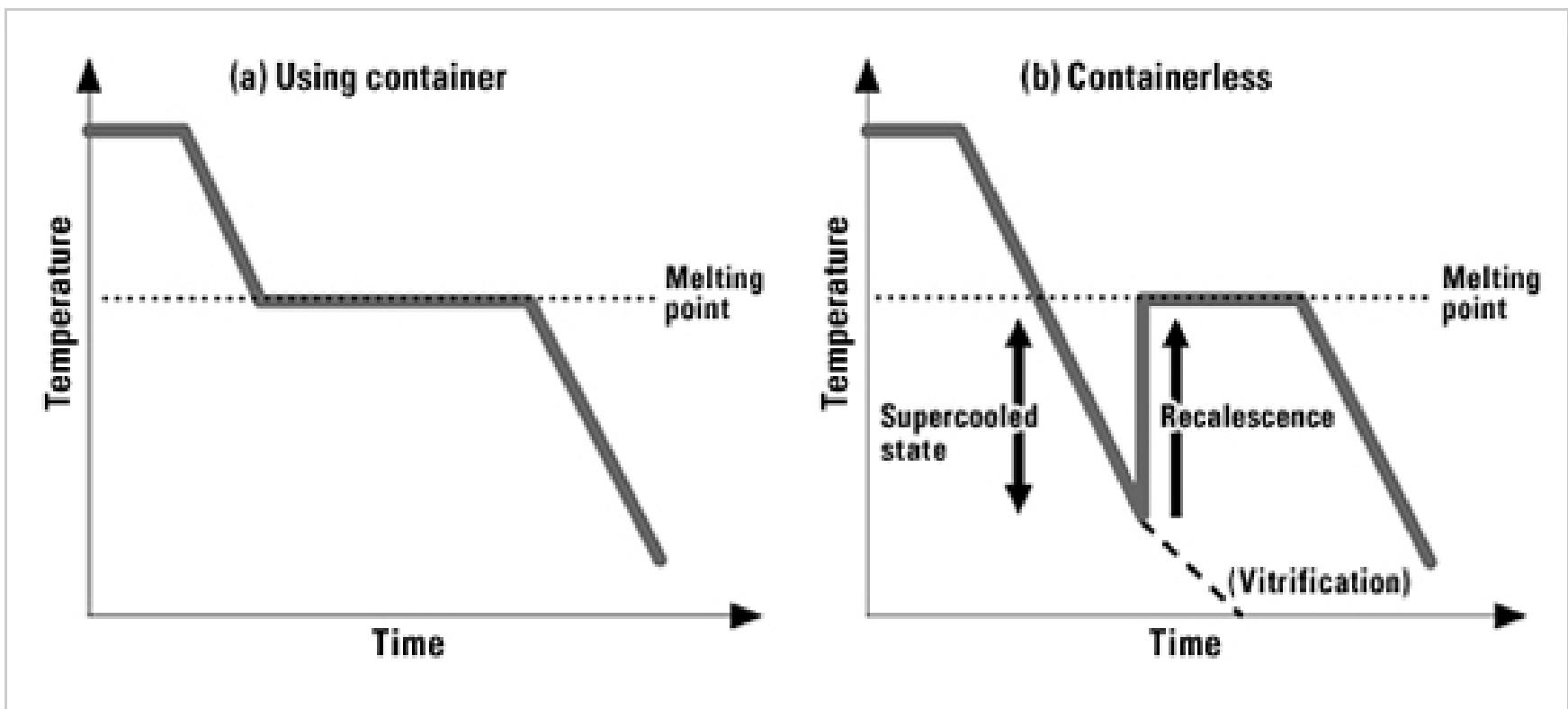
Electrostatic Levitation in KRISS

Containerless equipment: close to homogeneous nucleation

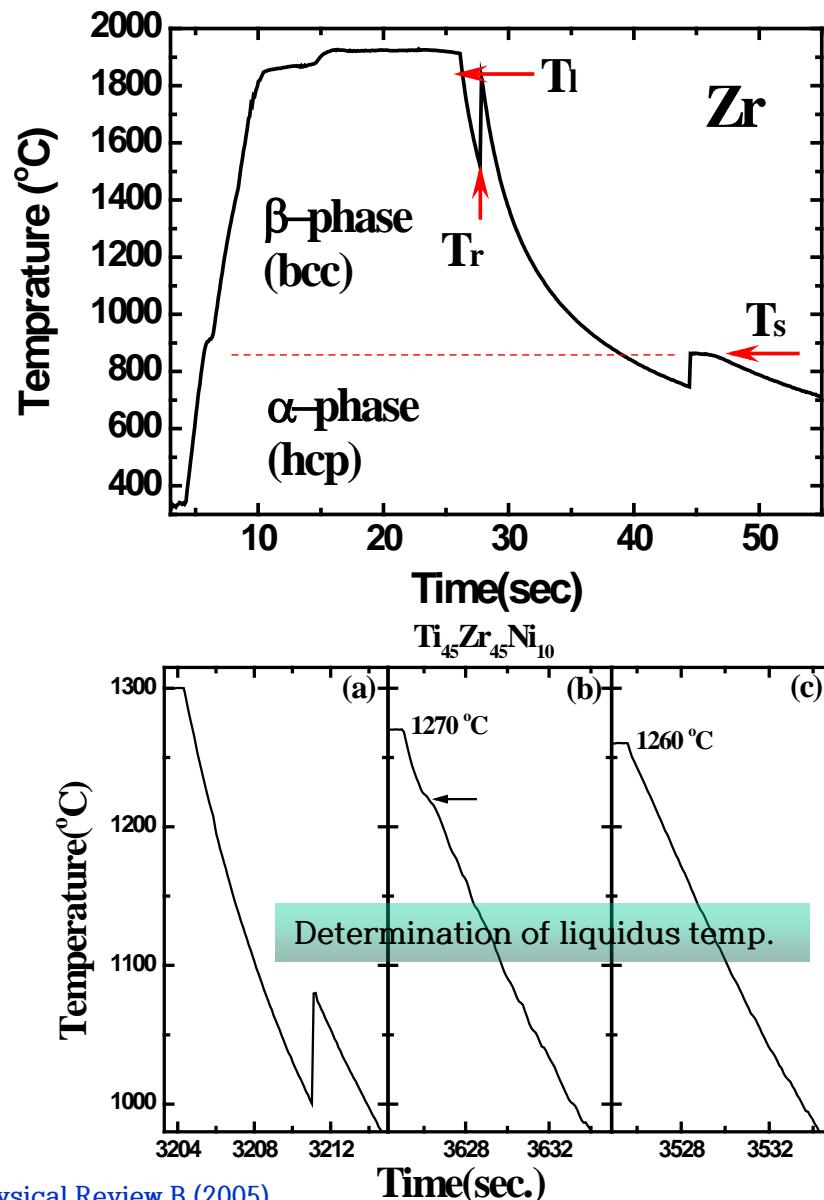
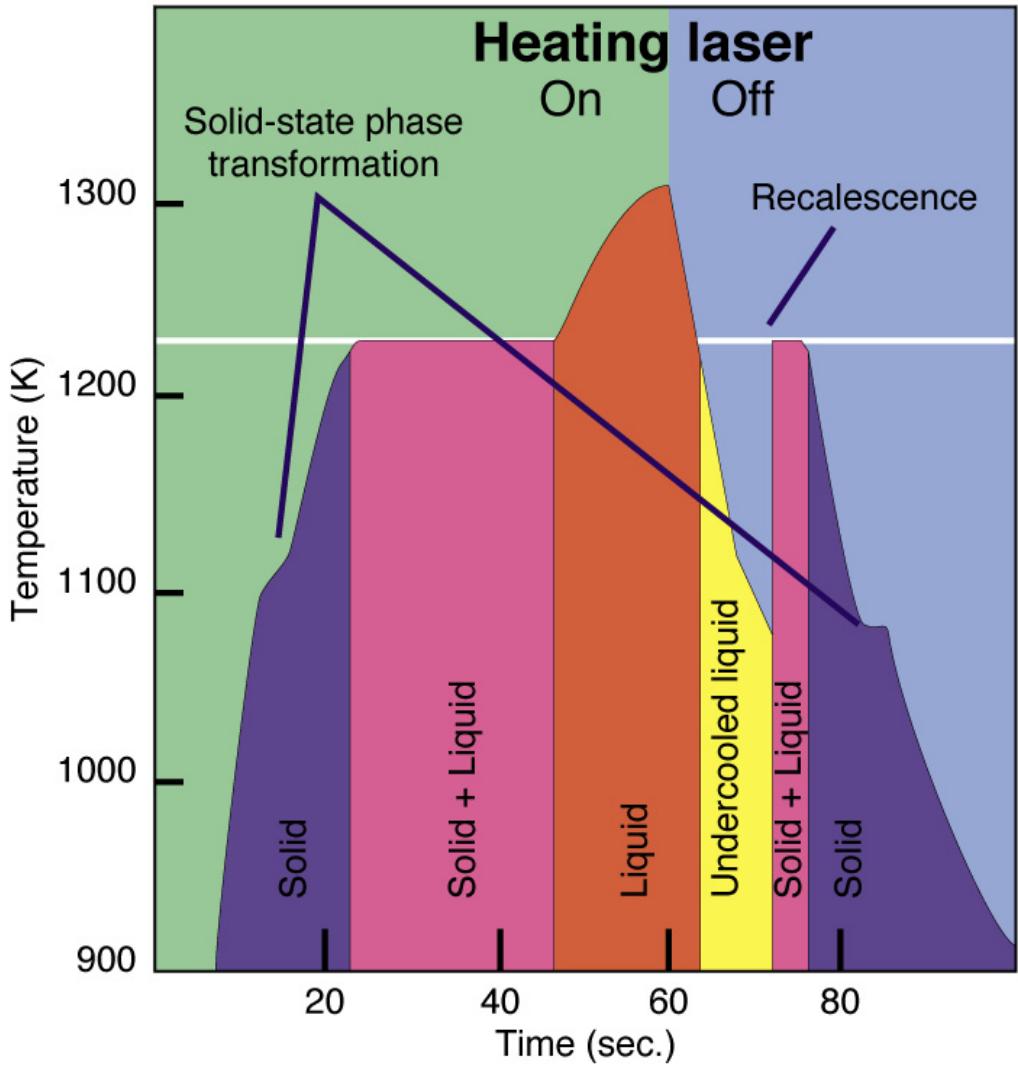


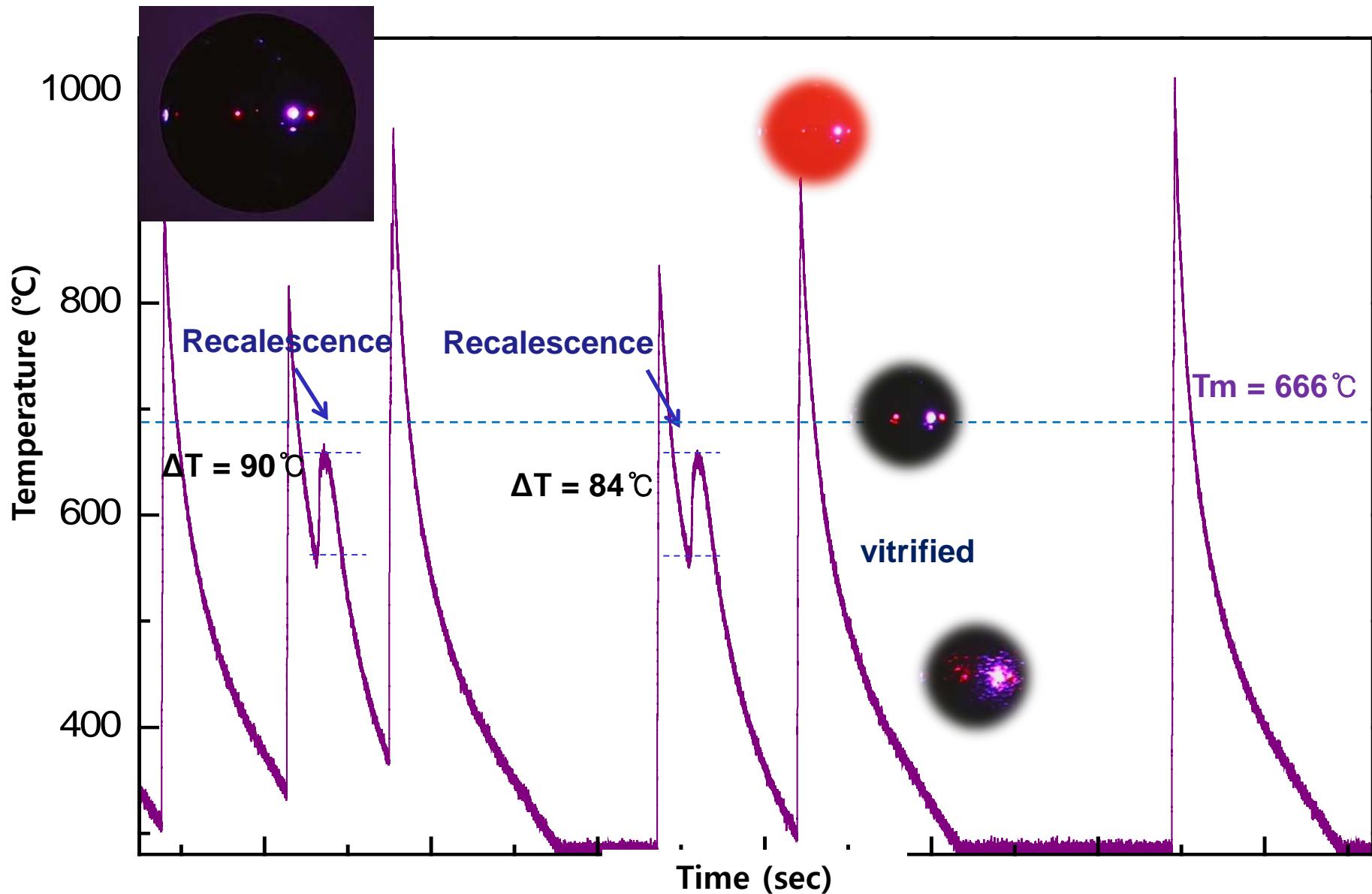


- ▶ No solid containers, No impurities from container
 - ▶ No heterogeneous nucleation site
 - ▶ Extremely large supercooling can be obtained (~ 100 °C), clear recrystallization
 - ▶ Metallic glass can be formed through free cooling



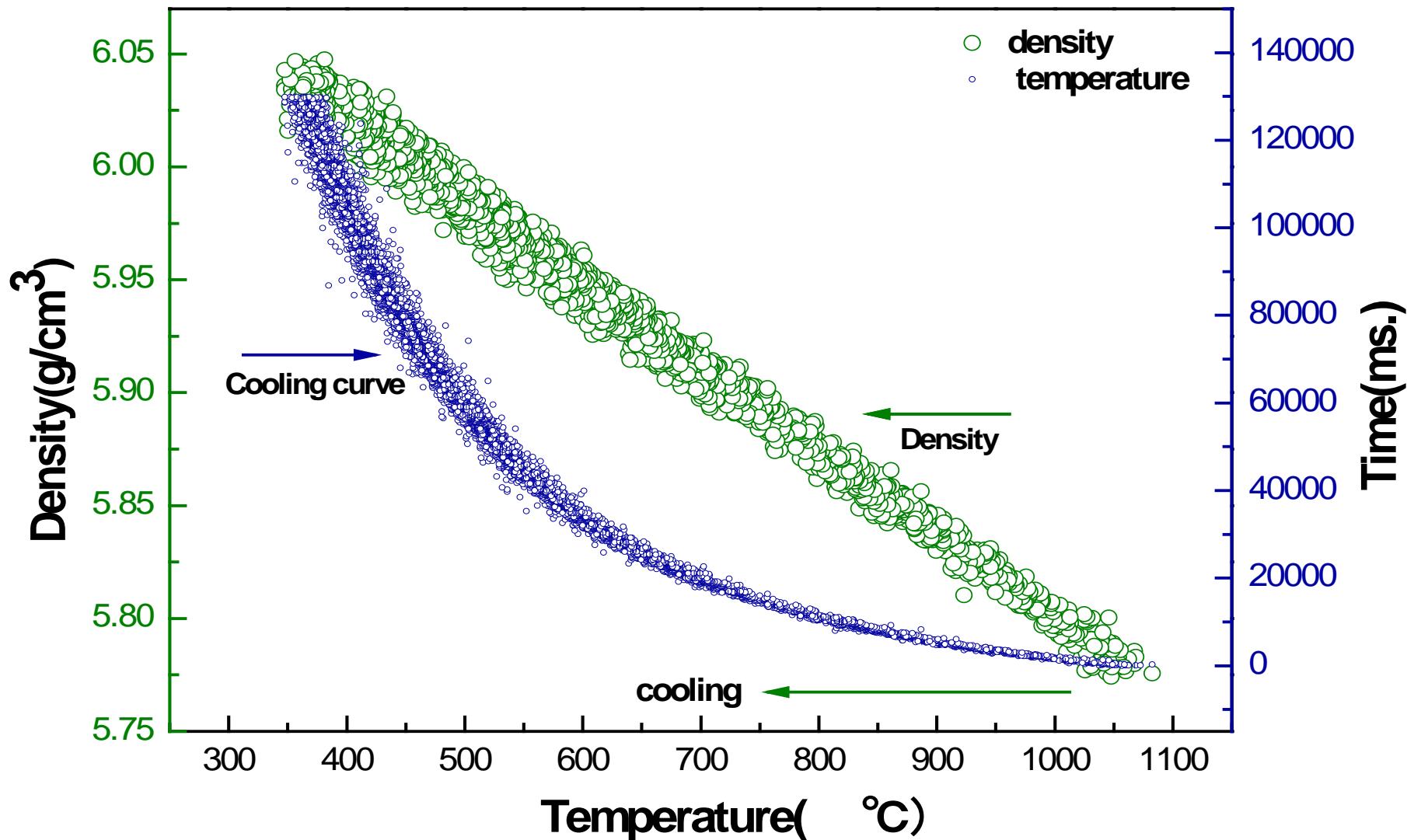
Melting and Freezing Using ESL



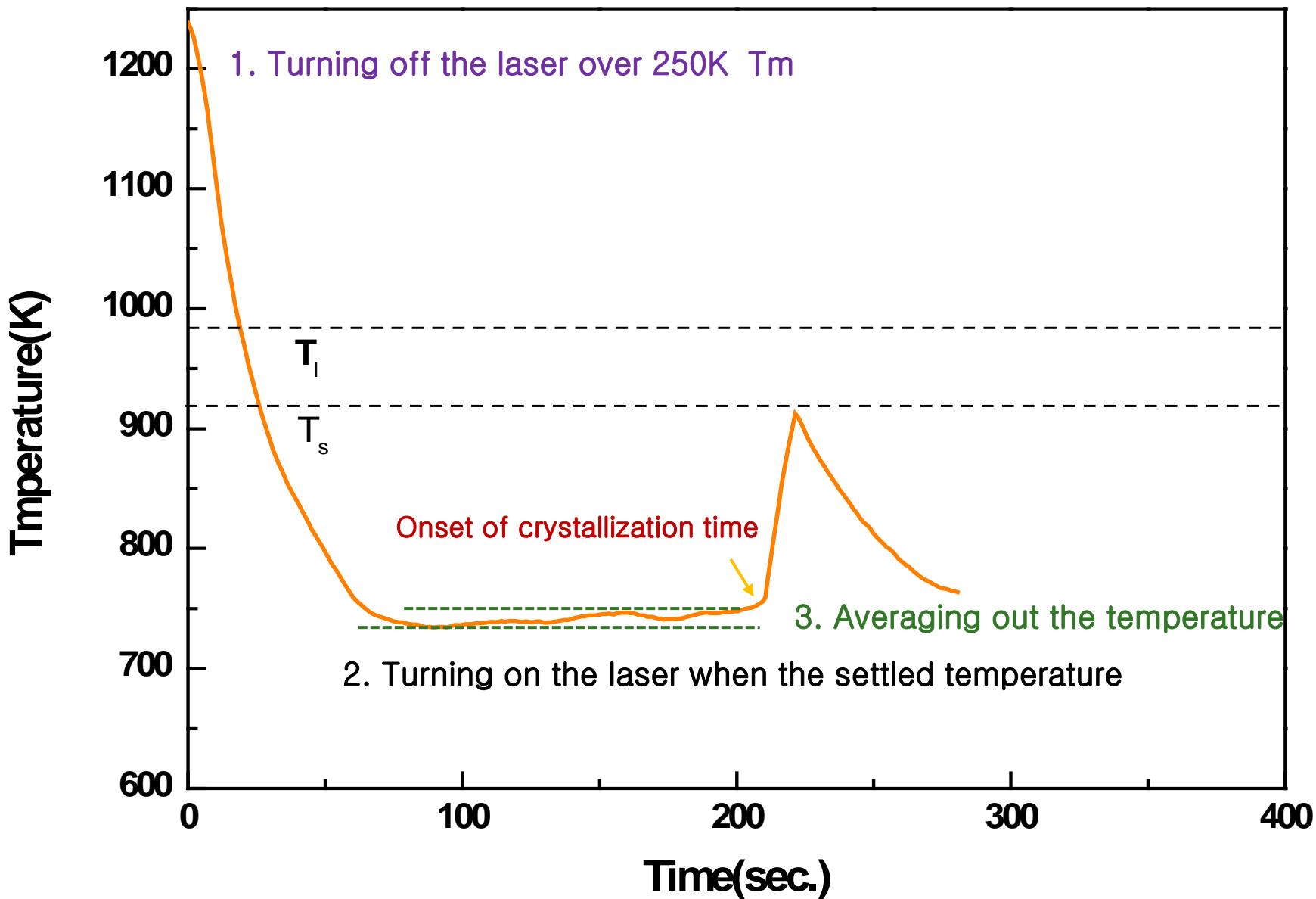
Cyclic cooling curves of $Zr_{41.2}Ti_{13.8}Cu_{12.5}Ni_{10}Be_{22.5}$ 

Cooling curve and density temperature profiles of $Zr_{41.2}Ti_{13.8}Cu_{12.5}Ni_{10}Be_{22.5}$

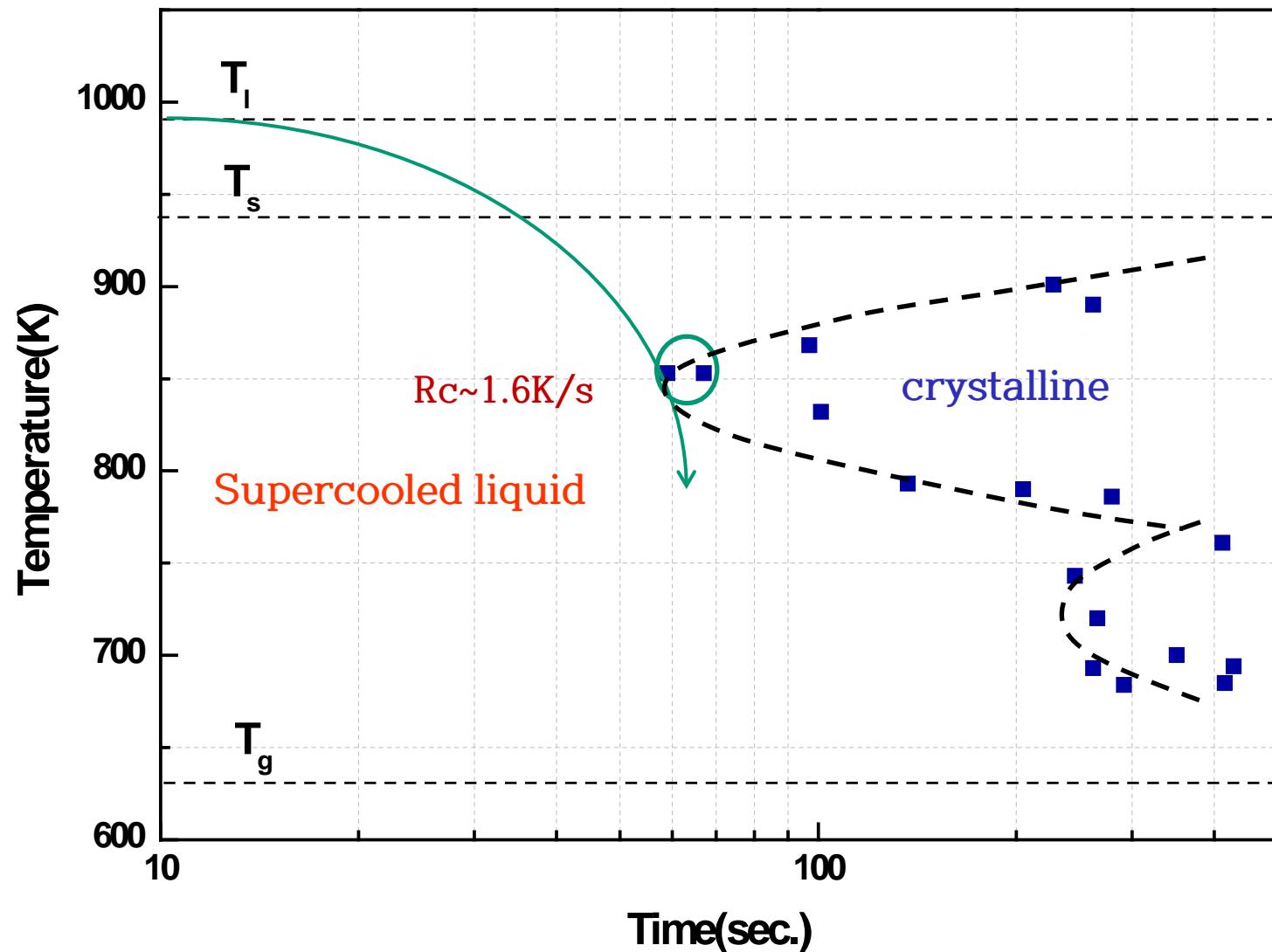
- Volume : CCD camera / Temperature measurement : pyrometer



Measurement of TTT diagram - $Zr_{41.2}Ti_{13.8}Cu_{12.5}Ni_{10}Be_{22.5}$



Measurement of TTT diagram - $Zr_{41.2}Ti_{13.8}Cu_{12.5}Ni_{10}Be_{22.5}$



Specific heat capacity

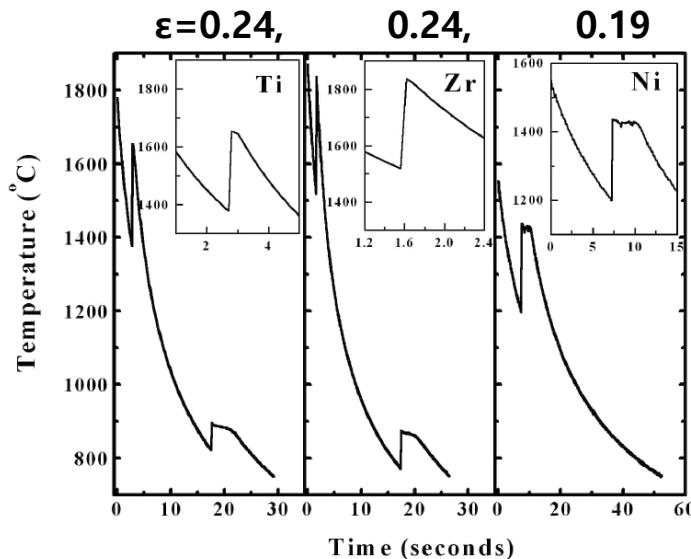
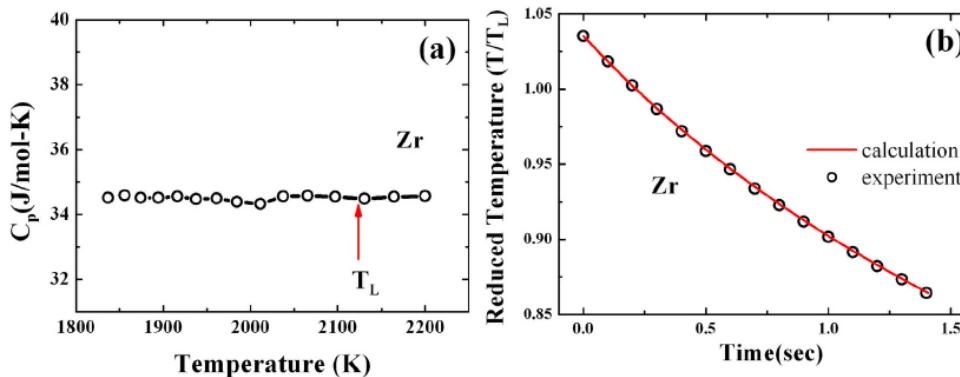


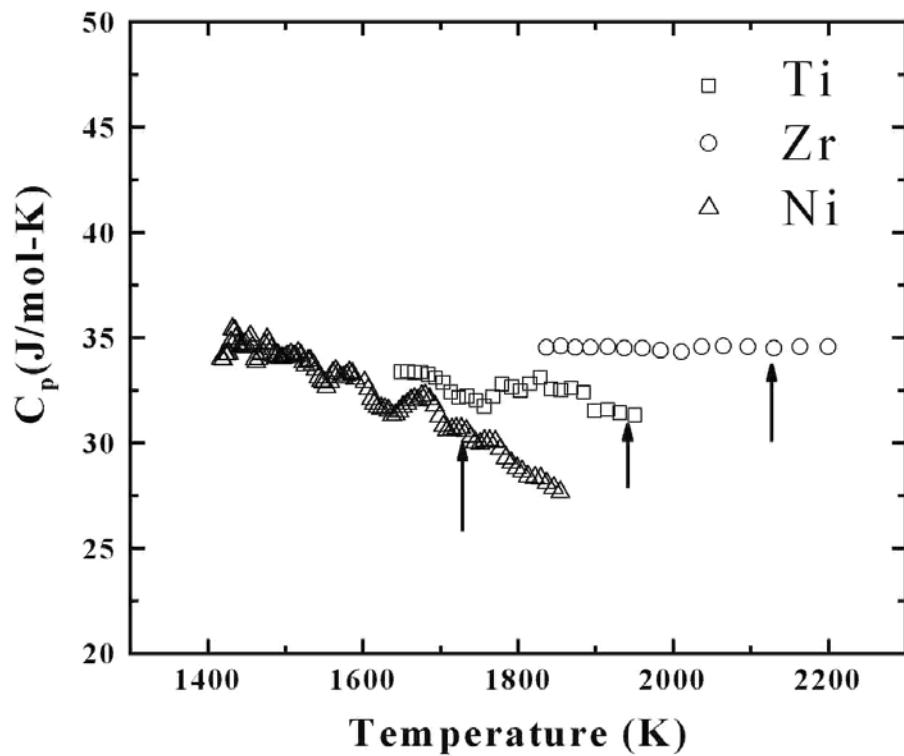
Figure 6.1. Free cooling curves of Ti, Zr and Ni, measured in the ESL. Inset figures show recrystallizations at high temperature.



$$t = \frac{mC_p}{4\sigma\varepsilon AT_r^3} \left(\ln \left(\frac{(T + T_r)(T_i - T_r)}{(T - T_r)(T_i + T_r)} \right) + 2 \tan^{-1} \left(\frac{T}{T_r} \right) - 2 \tan^{-1} \left(\frac{T_i}{T_r} \right) \right) \omega_{KRISS.re.kr}$$

$$mC_p \left(\frac{dT}{dt} \right) = 4\pi r^2 \sigma \varepsilon (T^4 - T_s^4)$$

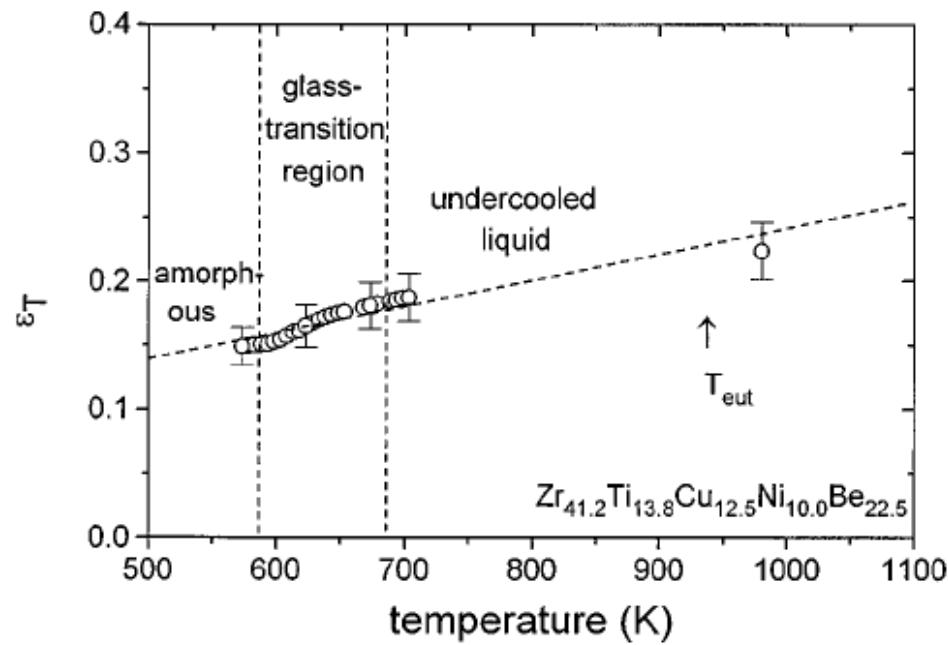
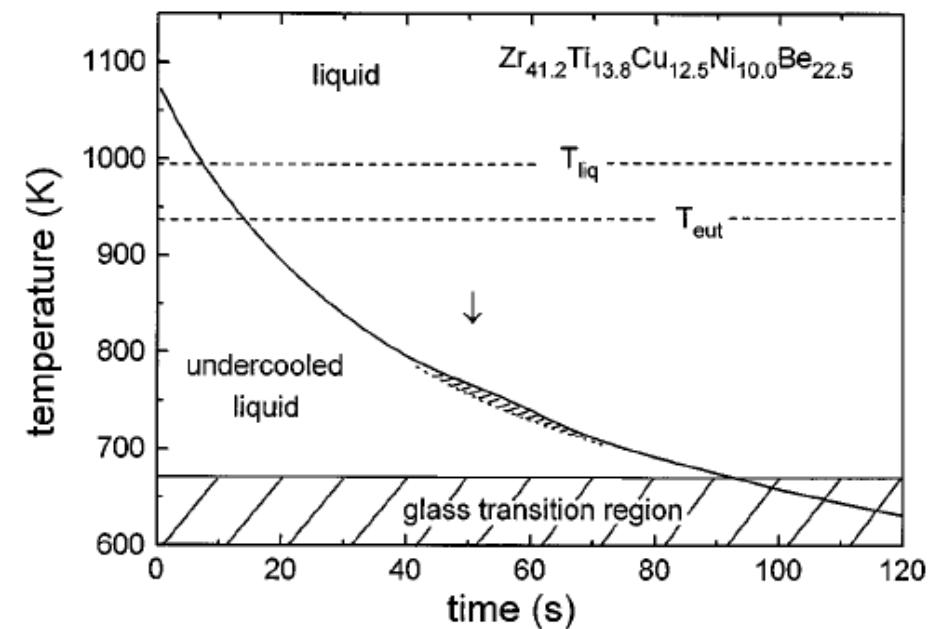
Specific heat of pure elements



Emissivity

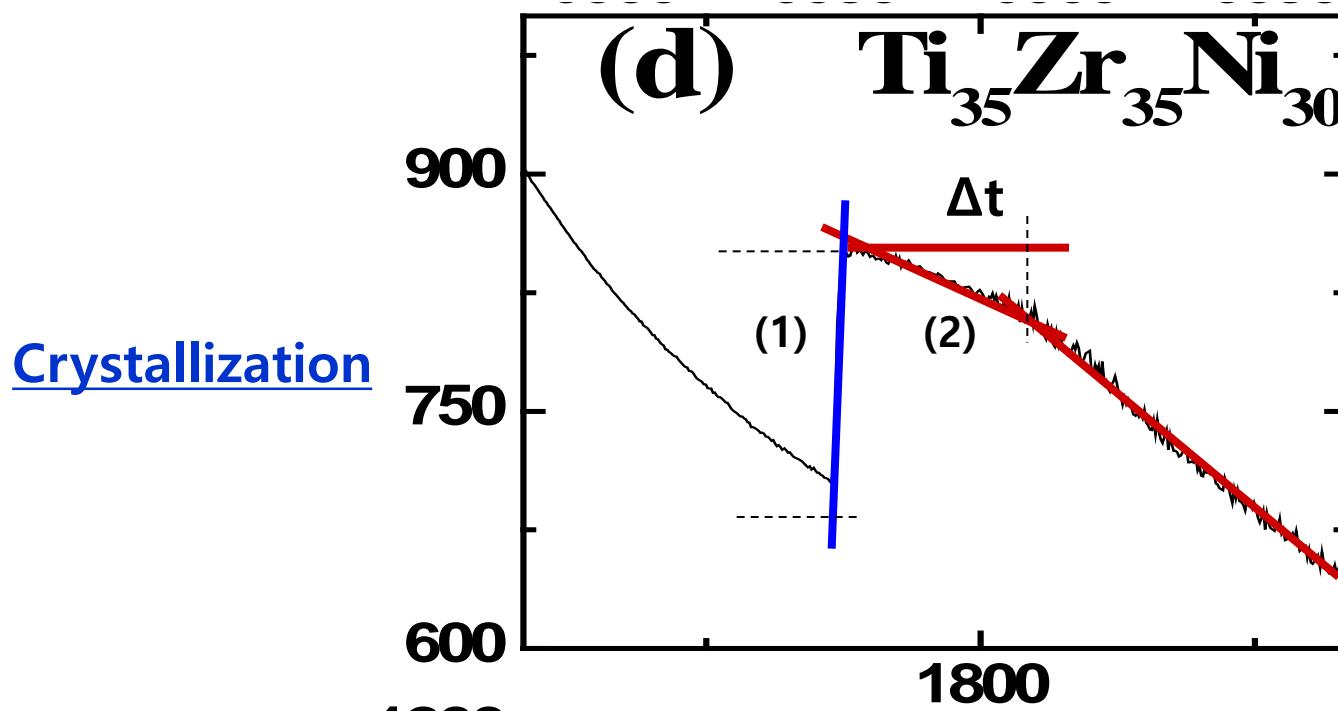
$$mC_p \left(\frac{dT}{dt} \right) + Power = 4\pi\sigma\varepsilon(T^4 - T_o^4)$$

Steady condition, $\left(\frac{dT}{dt} \right) = 0$



Fusion Enthalpy

$$\Delta H_f = (1) + (2) = C_p \Delta T_r + (4\pi\sigma\varepsilon(T_P^4 - T_o^4)\Delta t - 4\pi\sigma\varepsilon(T_P^4 - T_{end}^4)\Delta t)$$



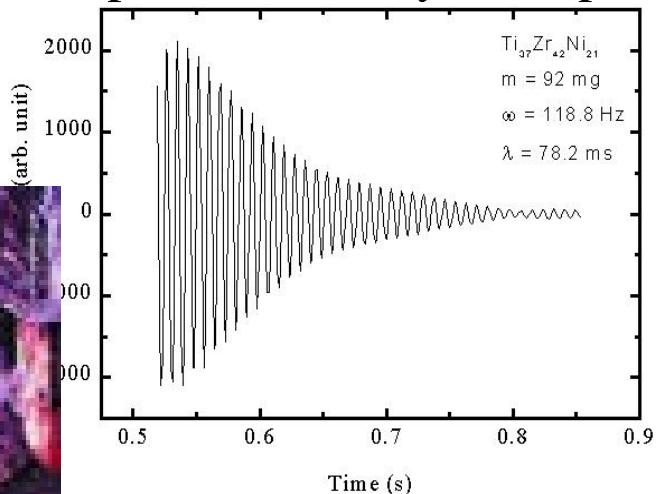
Viscosity & Surface Tension: Oscillation

Snapshot of surface oscillations in a Ni droplet

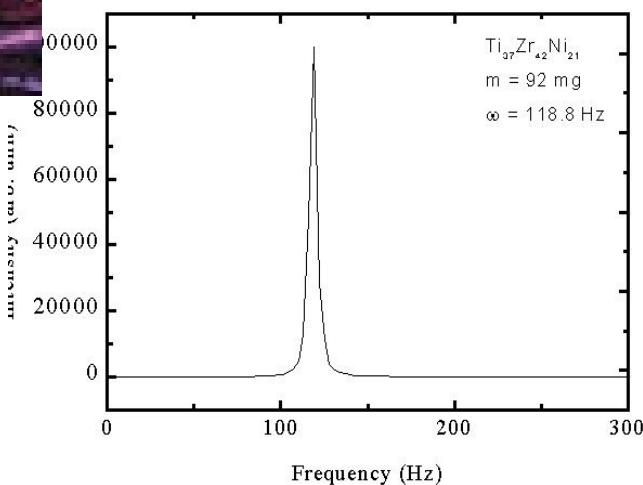


Damped oscillations

Exponential decay of amplitude



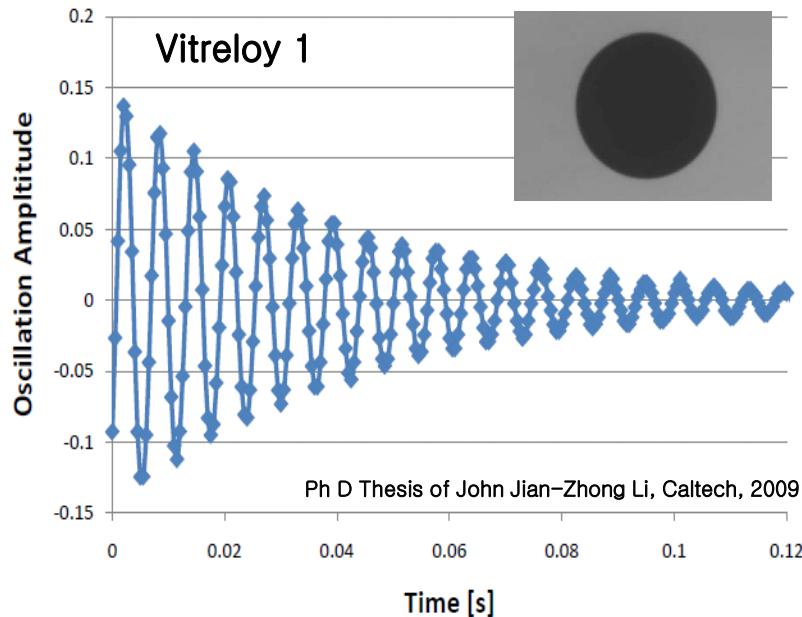
Power Spectrum Single frequency



Caution: No distortion from spherical symmetry
allowed multiple modes will be excited

► Measurement of thermophysical properties

- Volume : CCD camera / Temperature measurement : pyrometer
- Surface tension & Viscosity : oscillating the sample by with a pulse of AC voltage



$$\omega_2^2 = \frac{8\gamma}{\rho r_0^3}$$

Oscillation frequency

Surface tension

Radius when melt adopts a spherical shape

Density

$$\frac{1}{\tau_2} = \frac{5\eta}{\rho r_0^2}$$

Decay time constant

Viscosity

- Specific heat & total hemispherical emissivity : $\frac{m}{M} C_P \frac{dT}{dt} = -\sigma_{SB} \varepsilon_T A (T^4 - T_S^4)$
- Time- temperature-transformation curve : isothermal treatment

Oscillating drop 방식으로 고온에서 metal의 점도/ 표면 장력 측정 가능

Oscillating drop

- Induce surface oscillations in a levitating liquid droplet of radius ‘ R_o ’, mass ‘ m ’
- Measure the frequency of oscillation (ω)
- Measure the damping constant (λ)
- Damped resonant oscillations:

$$R = R_0(1 + \delta \cos(\omega t)e^{-\lambda t}) \quad \text{Rayleigh (1879)}$$

- Resonant frequency determined by surface tension:

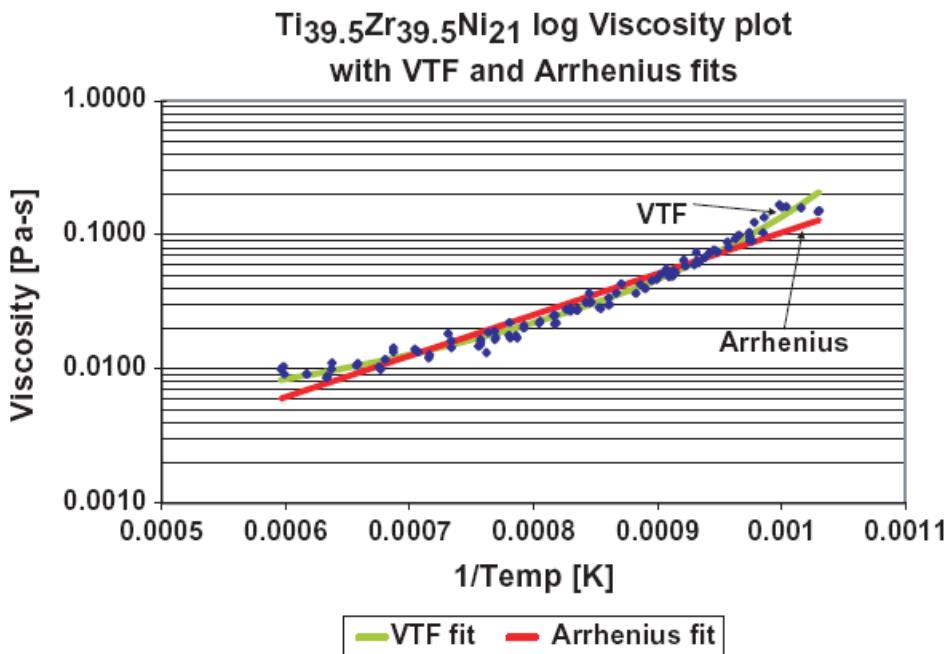
$$\omega_l = \sqrt{\frac{l(l-1)(l+2)\gamma}{\rho R_o^3}}$$

- Damping determined by viscosity:

$$\lambda_l = \frac{(l-1)(2l+1)\eta}{\rho R_o^2} \quad \text{Lamb (1881)}$$

High Temp. Viscosity

JOURNAL OF APPLIED PHYSICS 100, 103523 2006



Hyers, et.al., Philosophical Magazine Vol. 86, 2006(341–347)

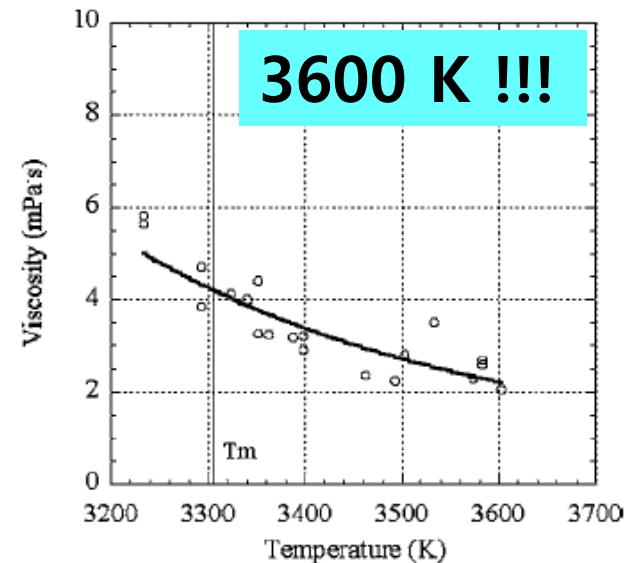


FIG. 5. Viscosity of equilibrium and nonequilibrium liquid Os as a function of temperature

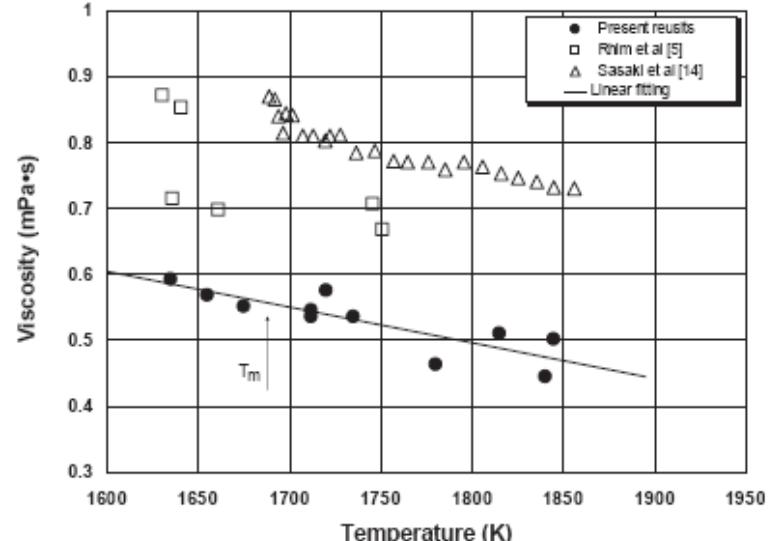


Fig. 8. Viscosity of molten silicon as a function of temperature.

High Temp. Surface Tension

Hyers, et.al., Philosophical Magazine Vol. 86, 2006(341–347)

JOURNAL OF APPLIED PHYSICS 100, 103523 2006

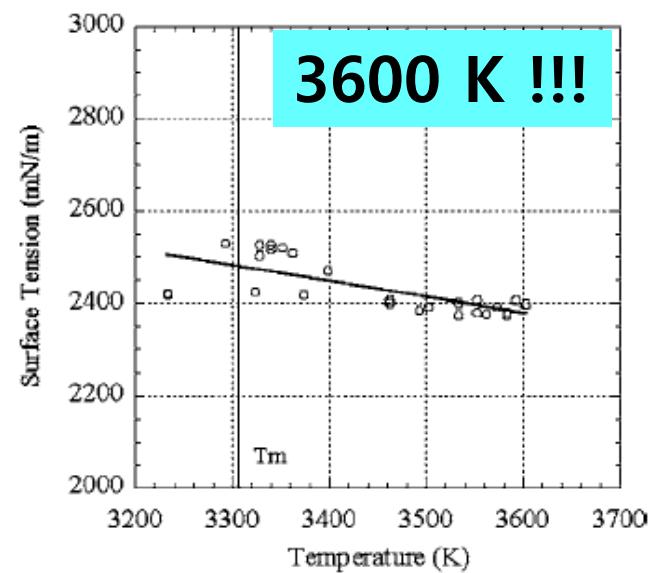
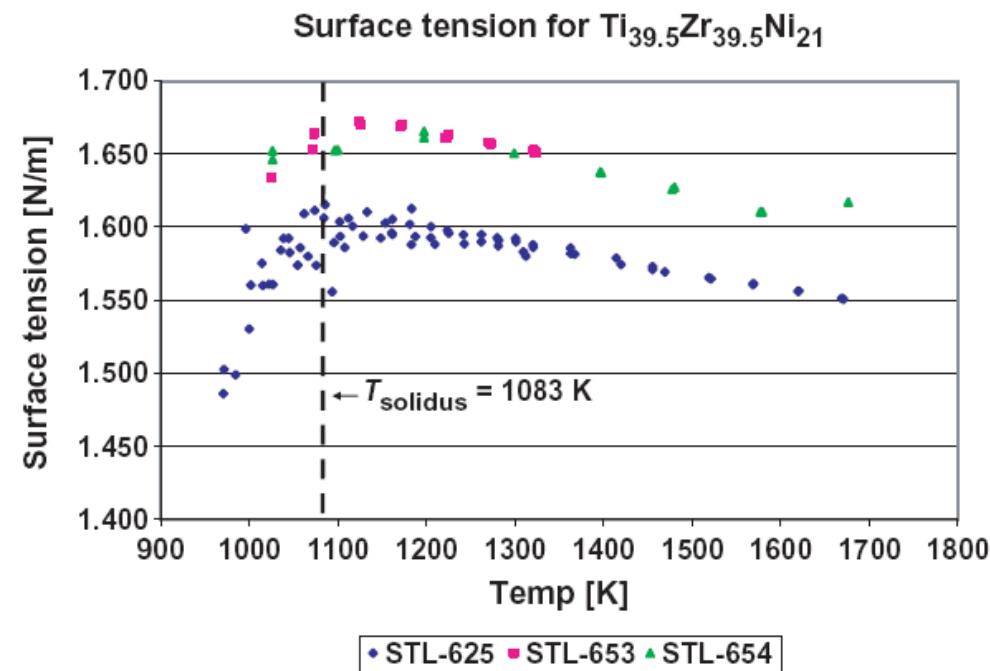


FIG. 4. Surface tension of equilibrium and nonequilibrium liquid Os as a function of temperature.

Density

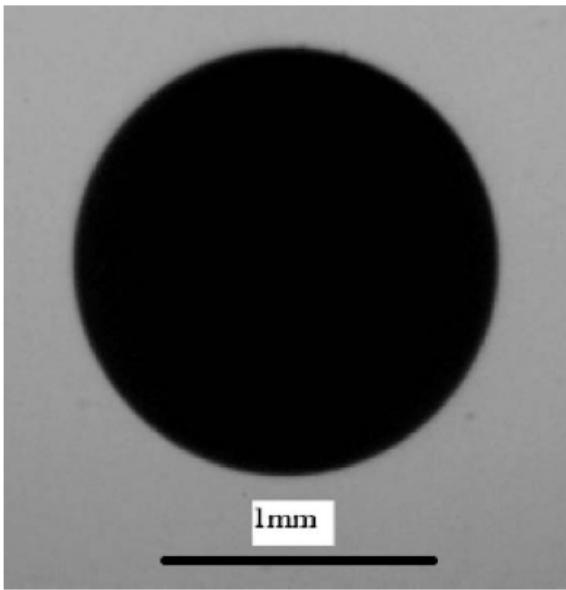


Fig. 2. A typical side view of a levitated molten silicon from which the density and the specific volume could be extracted.

Paradis, et.al., JOURNAL OF APPLIED PHYSICS 100, 103523 2006

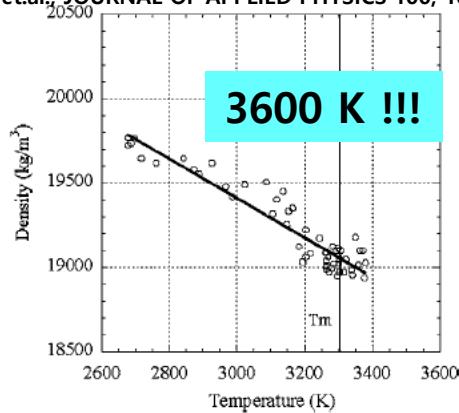


FIG. 3. Density of equilibrium and nonequilibrium liquid Os as a function of temperature.

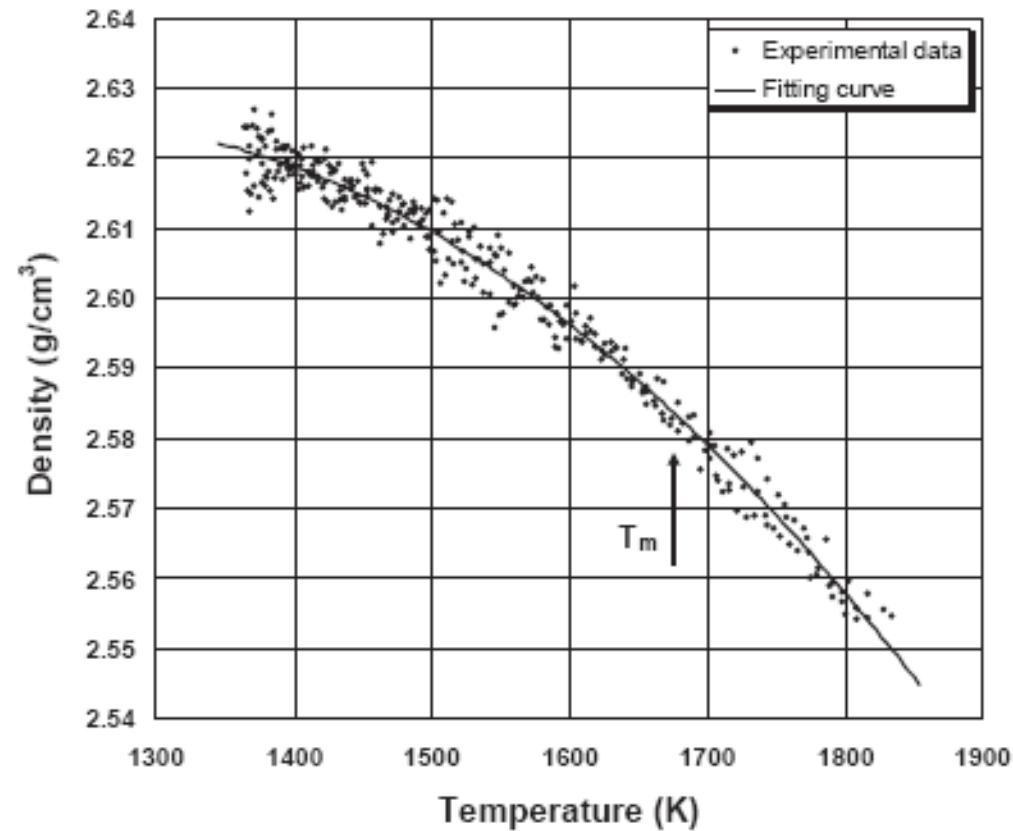


Fig. 4. Temperature dependent density of molten silicon.

Crystallization: Undercooling of Os

Paradis, et.al., JOURNAL OF APPLIED PHYSICS 100, 103523 2006

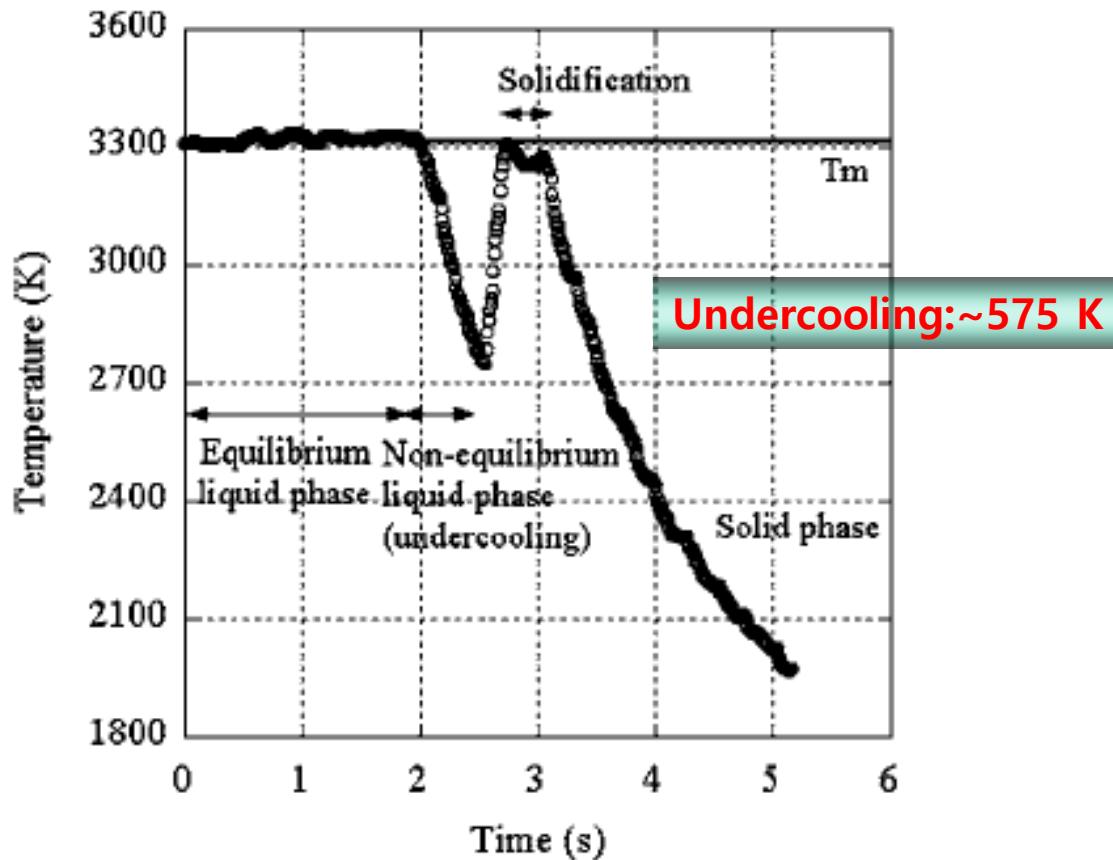
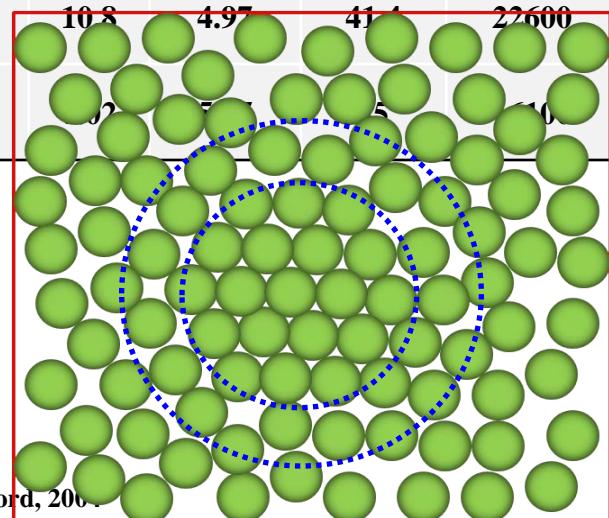


FIG. 2. Temperature history for an Os sample (diameter: ~ 1.76 mm; mass: 64.18 mg) showing heating slightly above the melting temperature (~ 3340 K), a radiative cooling rate of 1015 K/s, an undercooling of ~ 575 K, recalescence, and solidification.

Interfacial free energy of some elements

	$\frac{\Delta T_r}{\Delta T_{hyp}}$	$\sigma^{[1]}$	σ	$\alpha = \frac{a}{\sigma/\Delta H_f}$	r^*	ρ	$\eta_m^{[2]}$	C_p	$\Delta H_f^{[3]}$
	(K)	(J/m ²)	(J/m ²)		(nm)	(g/cm ³)	(10 ⁻³ Pa/s)	(J/mol·K)	(J/mol)
Ti	309 341	0.168	0.141 0.152	0.42 0.454	1.46 1.43	4.11	5.2	42.67	14550
Zr	332 345	0.158	0.154±0.009 0.159±0.010	0.410 0.423	1.54 1.52	6.08	4.67	42.5	19300
Hf	339 339	0.229	0.193±0.012	0.404	1.47	12.24	7.07	60.3	24070
Nb	443 563	0.262	0.258±0.016 0.303±0.024	0.394 0.462	1.33 1.23	7.63	4.94	52.0	29300
Rh	413 546	0.279	0.261±0.018 0.313±0.029	0.439 0.527	1.08 1.19				
Fe	195 357	0.269	0.158 0.228	0.33 0.478	1.45 1.15				

- Turnbull : $\alpha = 0.45$ for most metals



¹⁾ B. Vinet, L. Magnusson, H. Fredriksson, P. J. Desré, *J. Colloid Interf. Sci.* 255 (2002) 363

²⁾ T. Ishikawa, P.-F. Paradis, J. T. Okada, Y. Watanabe, *Meas. Sci. Technol.* 23 (2012) 025305

³⁾ W. F. Gale,²⁶ G. C. Totemeier, in "Smithells Metals Reference Book", 8th ed. Butterworth-Heinemann, Oxford, 2006.

Development of extreme condition endurance materials

Thermophysical properties

Specific heat capacity

$$C_p$$

Thermal conductivity

$$K_T$$

Fusion enthalpy

$$\Delta H_f$$

Growth rate

$$\dot{G}$$

Gibbs free energy

$$\Delta G$$

Emissivity

$$\epsilon$$

Undercooling temperature ΔT

Melting temperature T_m

Transformation temperature T_c

Annealing

Phase transformation

- Nucleation and growth
- Recrystallization
- Martensitic transformation
- Spinodal decomposition
- Phase separation

✓ Development
of new material

Simulation/Modeling

Heating & Cooling rate

Thermal expansion

$$\alpha$$

Nucleation rate

$$\dot{N}$$

Interfacial free energy

$$\sigma$$

Density

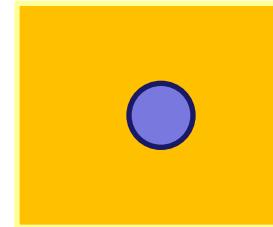
$$\rho$$

Surface tension

$$\sigma$$

Melting and Crystallization are Thermodynamic Transitions

Solidification: **Liquid** \longrightarrow **Solid**



<Thermodynamic>

- Interfacial energy $\rightarrow \Delta T_N$

Liquid

T_m Undercooled Liquid

Solid

No superheating required!

- Interfacial energy \rightarrow No ΔT_N

$$\gamma_{SL} + \gamma_{LV} < \gamma_{SV}$$

Melting: **Liquid** \longleftarrow **Solid**



Incentive Homework 2:

superheating이 일어나는 경우 정리 PPT 3 page 이내

Nucleation

* *Homogeneous Nucleation of crystal in supercooled liquid*

→ Well-defined by Turnbull and his coworker theoretically / experimentally.

* *Heterogeneous Nucleation*

→ detailed theory ~ less satisfactory

Nucleation ~ a function of the temperature in liquids that are not in motion
but In practice, liquids are often exposed to dynamic conditions.

< Two main type of dynamically stimulated nucleation >

1) completely metastable supercooled liquid containing no crystal
→ Nucleation by friction, ultrasonic vibration, pressure pulse , etc.

2) A phenomenon that the # of crystals is greatly increased by dynamic methods in solidifying liquid → It is difficult to conclude that it is not due to the fragmentation of pre-existing crystals.

* *Dynamically Stimulated Nucleation*

→ very poor understood

Chapter 4. microscopic Heat Flow Considerations

4.1 Qualitative Observation

Solidification: Liquid \rightarrow Solid

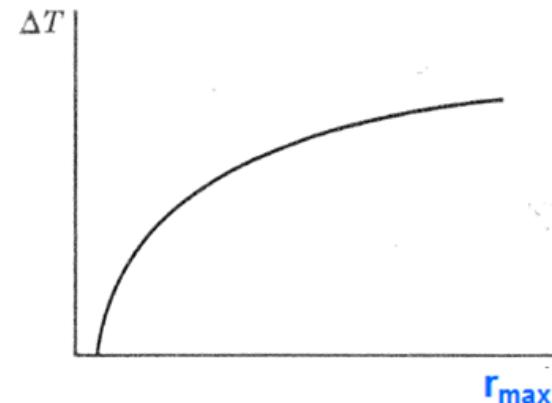
Presence of "Metastable supercooled liquid"

1) Atomic consideration

→ If it is curved, "escape angle" changes with curvature.

$$\therefore T_E, \text{ small crystal} < T_E, \text{ large crystal}$$

Thus, at any temperature below T_E , there is a radius of curvature at which the rates of melting and of freezing are equal. = critical radius r^*



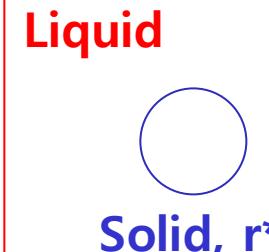
2) Thermodynamic treatment of equilibrium access a curved interface

Extra pressure ΔP due to curvature

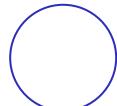
For incompressible solid,

$$\frac{L\Delta T}{T_E} = \frac{2\gamma_{SL}}{r^*}, \quad \text{or} \quad r^* = \frac{2\sigma T_E}{L\Delta T}$$

$\Delta H, \Delta S$: independent of temperature



Liquid



Solid, r^*

$$T_E + \Delta T (-) \text{ 면, } R_M < R_F \rightarrow r \uparrow \\ \rightarrow T_E \rightarrow T_E'' \uparrow \rightarrow \Delta T (-) \uparrow \rightarrow R_M \ll R_F$$

For small departures from equilibrium, the rate is approximately proportional to the departure (ΔT); however, **the actual rate depends upon the crystallographic orientation of the interface.**

It should be emphasized that the foregoing remarks relate to the actual temperature of the interface itself; this may be different from the temperature of the liquid or solid at even a short distance from the interface because of the “**latent heat of fusion**” that is generated at the interface during solidification or is absorbed there during melting.

Who can explain the clear difference between two movies?

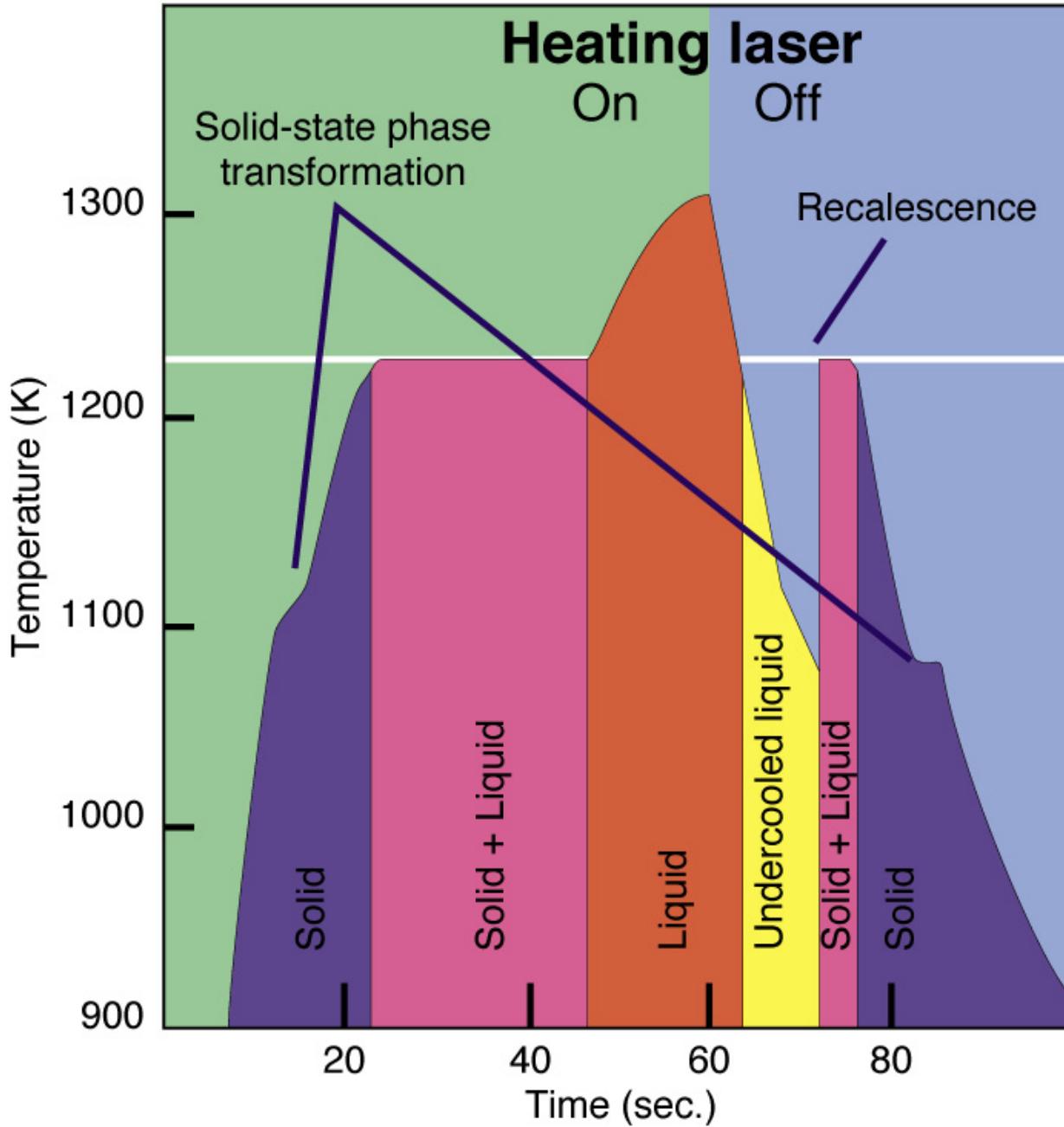


ZrCuAl alloy with non-purified Zr



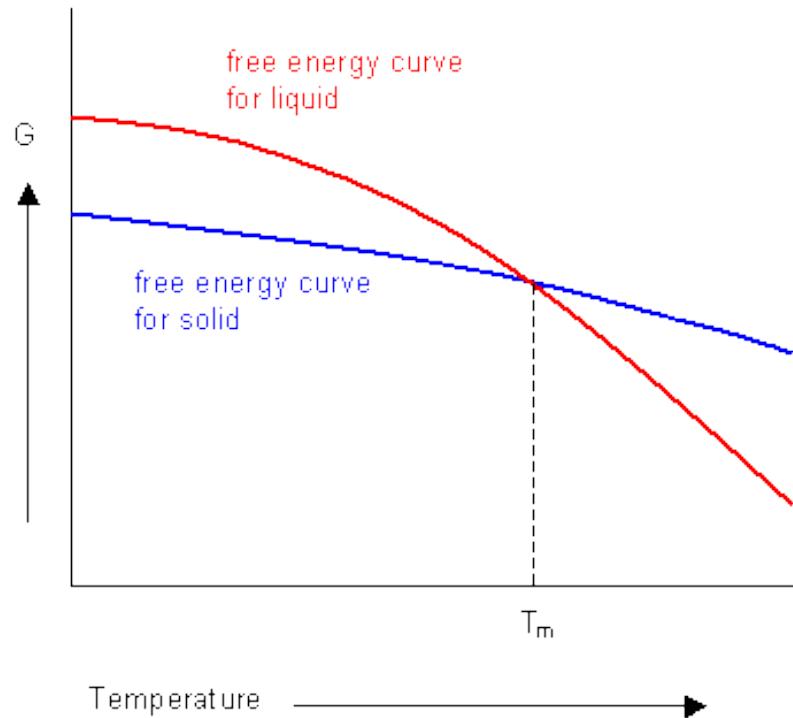
ZrCuAl alloy with purified Zr

Melting and Freezing Using ESL



* Broken bond model → calculation of the E of solid/ liquid interface

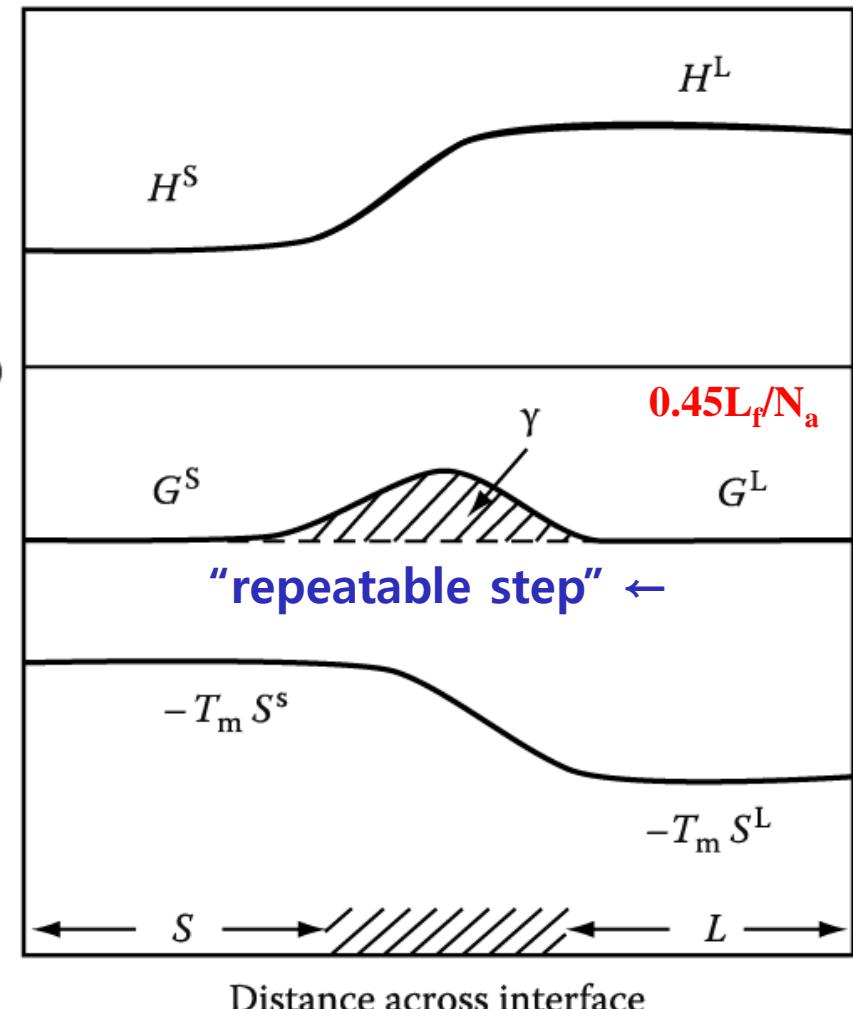
at equilibrium melting temp.



$$\gamma_{SL} \approx 0.45 \gamma_b \quad (= 0.15 \gamma_{SV})$$

for the most metals

$$\gamma_{SV} > \gamma_{SL} + \gamma_{LV}$$



Showing the origin of the solid/ liquid interfacial energy, γ

$$T_{\text{interface}} < T_E \rightarrow \text{solidification } \uparrow \rightarrow \text{latent heat } \uparrow \rightarrow \Delta T \downarrow$$

The “removal of latent heat” therefore controls the rate at which solidification can continue, and the interface temperature adjusts itself so that it corresponds to the rate of solidification determined by the externally imposed thermal conditions.

The local rate of growth at any point on the surface therefore depends on the thermal conditions and on the orientation of the surface, since this influences the relationship between temperature and rate of growth.

The interplay of the anisotropy of growth rate with the effects of the geometry of the surface on local heat flow is responsible for the very complicated morphology that may occur during solidification.